GLOBAL SEMICONDUCTOR ALLIANCE
30 YEARS
1994-2024

GSA

2024 INTERNATIONAL SUMMIT

Core to Semiconductor Infinity

OCTOBER 28

VeriSilicon 芯原

Silicon Platform as a Service (SiPaaS®)

VeriSilicon NPU IP

enables

100+ Million
Chip shipments

72
Customers

128
SoCs

10
Application segments

5nm FinFET

design capability drives

- Autonomous driving/ADAS SoC meeting Functional Safety standards
- Media accelerator SoC supporting AV1 with AI functions

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GSA is Where Leaders Meet to establish an efficient, profitable, and sustainable high technology global ecosystem encompassing semiconductors, software, solutions, systems, and services. A leading industry organization that represents 300+ corporate members, including more than 120 public companies, GSA provides a unique, neutral platform for collaboration, where global executives interface and innovate with peers, partners, and customers to accelerate industry growth and maximize return on invested and intellectual capital. Members of the GSA represent 77 percent of the $535B+ semiconductor industry and continue to grow. For more information, visit www.gsaglobal.org.

WELCOME TO THE 2024 GSA INTERNATIONAL SUMMIT

On behalf of the Global Semiconductor Alliance, I am thrilled to welcome you to the GSA International Summit. This event offers a unique opportunity to bring together leaders and innovators from across the global semiconductor industry to explore emerging trends, tackle complex challenges, and share insights that will shape the future of our industry.

The theme of the summit, Core to Semiconductor Infinity, reflects the limitless potential of semiconductors in driving technological advancements and global economic growth. As the foundation of modern innovation, semiconductors are at the heart of emerging technologies like generative AI, automotive evolution, and advanced high-performance computing. These advancements, coupled with the challenges of today's dynamic geopolitical landscape, make it imperative that we address key issues such as supply chain resilience, sustainability, and industry collaboration.

We are honored to have an exceptional lineup of speakers who bring diverse perspectives and expertise to the table. I encourage you to make the most of this gathering—take the time to connect, exchange ideas, and collaborate with peers from around the world. Together, we can forge the path ahead and drive innovation that will lead us through both challenges and opportunities.

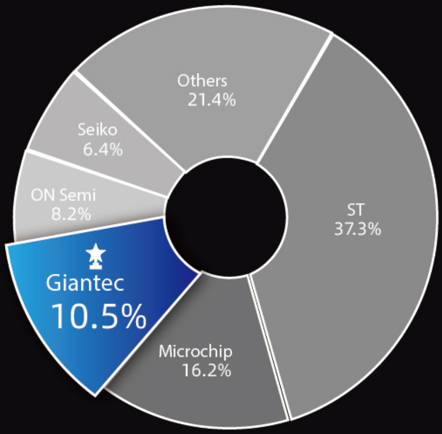
I would also like to extend a heartfelt thank you to our sponsors, whose invaluable support has made this event possible. Their partnership underscores the collaborative spirit that defines our industry.

Thank you for being part of the GSA International Summit. I look forward to the discussions and ideas that will emerge as we work together to shape the future of semiconductors.

Jodi Shelton

CEO, GSA

Ranked Top 3 at Worldwide EEPROM Market



Unit: Million dollars

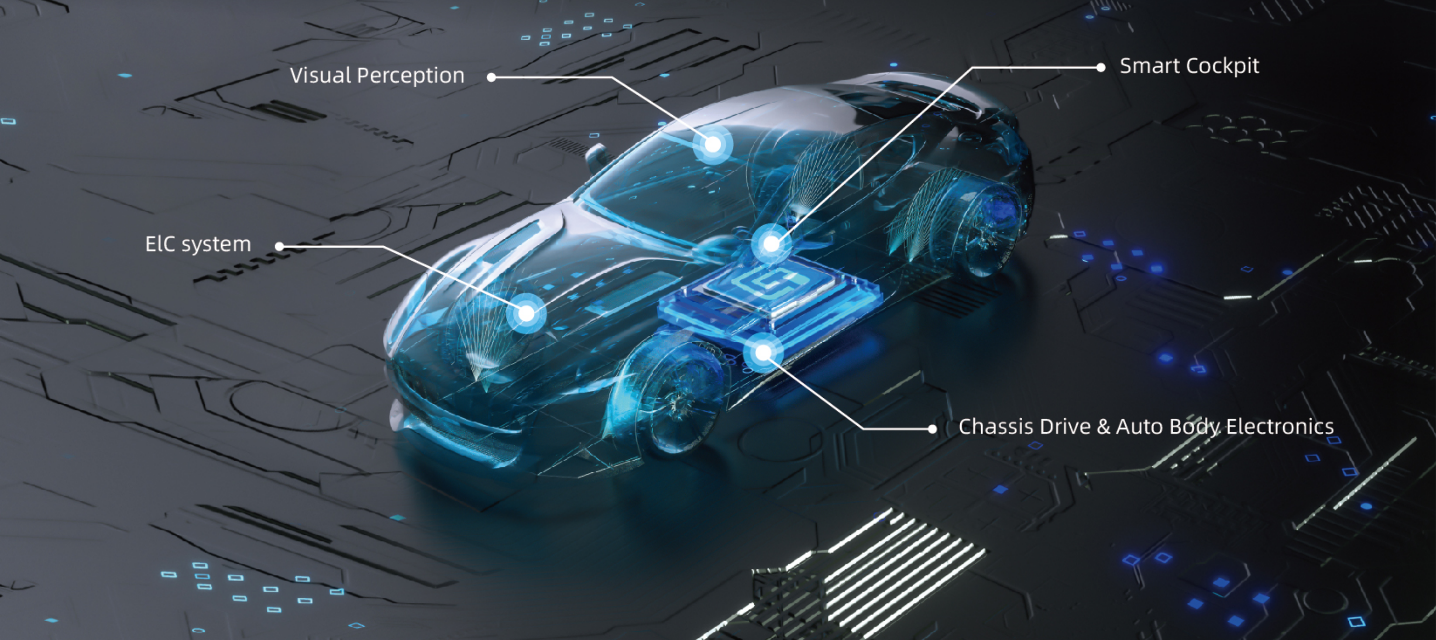
Ranking	Supplier	Sales in 2023
1	ST	322
2	Microchip	140
3	Giantec	91
4	ON	71
5	Ablic(Seiko)	55
6	Others	184
Sum		863

Source: Web-feet Research (Apr,2024)

Leadship in Automotive Memories

Our products

- Cover automotive 125°C and 105°C EEPROM and NOR Flash
- Reach core automotive applications, fully introduced with leading car manufacturers
- Achieved AEC-Q100 Grade 1 Automotive Qualification Standard
- Received Declaration of Conformity for the IATF 16949:2016(Compliance)



2024
GSA INTERNATIONAL SUMMIT

Core to Semiconductor Infinity

AGENDA

13:00	**Registration** 2F, Regent Ballroom 丽晶厅
13:30	**Welcome Remarks** Jodi Shelton / CEO / GSA Qiwei Ren / CEO / UNISOC & GSA BOD Member
13:50	**Global Industry Collaboration** Christopher Thomas / Chairman and Founder / Integrated Insights
14:10	**Emerging Semiconductor Ecosystems** Farhat Jahangir / Founder & CEO / GSME
14:30	**Impact of Generative AI For Semiconductors** **Chiplet-based High-end Intelligent Driving IC Design Platform** Wayne Dai / Chairman, President & CEO / VeriSilicon **RISC-V, the next Generation Architecture for AI** Marc Canel / Vice President, Business Development / Ventana Micro Systems
15:10	**Networking Break** 2F, Ballroom Foyer 丽晶厅前厅
15:40	**Global Semiconductor Market Outlook** Minyu Xiao / Associate Partner / McKinsey & Company
16:00	**Innovations And Emerging Technologies** **Automotive Security** Hassan Triqui / Co-founder, CEO & President / Secure-IC **Semiconductors and Innovation Frontier: Paving the Way for Advanced Technologies** Hongyu Wang / Regional President APAC / Bosch Sensortec GmbH Vice President / Bosch Semiconductors China
16:40	**Closing Remarks**
16:45	**VIP Reception** 2F, Ballroom Foyer 丽晶厅前厅
18:00	**VIP Dinner** 2F, Harmonia 绣餐厅


POWERING AI WITH
SILICON LEADERSHIP

MEET THE SPEAKERS

DR. QIWEI REN

CEO

UNISOC

Dr. Qiwei Ren received the bachelor and master degrees from Tsinghua University in 1992 and 1995 respectively, and Ph. D. from Delft University of Technology in 2002.

In 2001, he joined Philips Semiconductors in the Netherlands, worked for embedded memory development as senior designer and project leader.

In 2006, he joined the design center of Qimonda Technology in Xi'an, China, as the Design Director for DRAM product development. In 2009 he promoted the acquisition as co-founder and re-found the design center as Xi'an Sinochip Semiconductors Co. Ltd, worked as general manager. In 2015 the company was acquired again and renamed as Xi'an UniIC Semiconductors Co. Ltd. In 2018 he started to work as CEO of UNIC memory technology Co. Ltd in the same time. From 2022, he becomes the CEO of UNISOC (Shanghai) Technologies Co., Ltd..

In 2012-2017 he was part time professor in Xi'an Jiaotong University, and IEEE senior member for many years.

MEET THE SPEAKERS

CHRISTOPHER THOMAS

Chairman and Founder

Integrated Insights

Chris Thomas is the founder of Integrated Insights, an advisory firm serving the Boards, Chairpersons and CEOs of global companies; a Visiting Professor at Tsinghua University; a non-resident Senior Fellow in Artificial Intelligence and Emerging Technologies at the Brookings Institution; and a member of the Council on Foreign Relations.

Chris spent ten years as a Partner at McKinsey & Company, leading various efforts including the Asia Semiconductor Practice, the Global Digital Strategy Practice, and the Global IOT service line. Prior to McKinsey, Chris spent a decade at Intel. He was the General Manager of Intel China, the largest semiconductor business in China. Chris also held multiple executive roles at Intel's global headquarters. These roles included Chief of Staff to Intel's Chief Sales, Marketing, and Strategy Officer, where he advised on all key decisions for Intel's 5,000-person global salesforce.

Chris began his career as a private equity investor at The Blackstone Group in New York City and has served as a Board Director at Velodyne, the inventor of LiDAR. Chris is recognized as a leading global authority on the global semiconductor industry and the impact of US and Chinese technology policies. In 2021, the State Council of the People's Republic of China recognized Chris as a national-level foreign expert in science and technology. He received an MBA from Stanford Business School, where he was an Arjay Miller Scholar; a Master of Arts in Political Science from Stanford University; and a Bachelor of Science in Economics, summa cum laude, from the Wharton School.

MEET THE SPEAKERS

FARHAT JAHANGIR

Founder, President and CEO

GSME

Farhat is the founder and CEO of GSME, where he brings over 25 years of hands-on experience in the semiconductor industry. Farhat is an expert in product, test, quality, reliability, and supply chain areas covering various hi-speed communication ICs, MEMS-based and CE System-based product lines. In 2016, Farhat led Quantenna to its IPO, which paved the way for the company's acquisition by Onsemi for a staggering $1.1 billion in 2019.

As the General Manager/Vice President of Manufacturing at Onsemi, he successfully managed the 300mm EFK Fab as well as a revenue line exceeding $2 billion. Farhat is a recognized industry leader and uses his extensive experience to drive innovation in the field of semiconductor manufacturing. He began his career after graduating with a Master of Science in Electrical Engineering from the University of Arkansas.

MEET THE SPEAKERS

WAYNE DAI

Chairman, President and CEO
VeriSilicon

Dr. Wayne Dai founded VeriSilicon in August 2001 and has served as the chairman of the board of directors, President and Chief Executive Officer since then. Prior to founding VeriSilicon, Dr. Dai was the Co-Chairman and Chief Technology Officer of Celestry Technologies, Inc., an EDA company, which was acquired by Cadence Design Systems in 2002. Prior to that, he was the founder, chairman of the board of directors, and Chief Executive Officer of Ultima Interconnect Technology, Inc., one of the predecessor companies to Celestry.

Dr. Dai was the founding Chairman of the IEEE Multi-Chip Module Conference and IEEE Symposium on IC/Package Design Integration, Co-Chairman of the Program Committee of the 2010 International Green Energy Forum. He was an Associate Editor of IEEE Transactions on Circuits and Systems and an Associate Editor of IEEE Transactions on VLSI Systems. He has published more than 100 papers in technical journals and conferences and received the NSF Presidential Young Investigator Award from the President of United States in 1990. He was recognized as top ten venture-backed entrepreneurs and top ten talents of science and technology in China in 2005. He was honored with The Ernst & Young Entrepreneur of the Year in China in 2007. He won the ACE's Executive of the Year award in 2013, the Hurun Industry Achievement Award in 2014, the APAC Innovator of the year of WEAA in 2018, and was recognized as a "Leading Pioneer" in 2018 by Shanghai Smart City Construction, 2019 Contributor of the year and 2021 Outstanding Contributor of Industry Progress of WEAA, the 2021 Sci-Tech Innovation Golden Horse Awards Outstanding Leader award, 2023 Annual Outstanding Person of China IC Industry, and High Tech Contributor of the Year of 2023 Compass Tech Award. He is currently the Vice Chairman of Global Innovation Center, the Executive Vice President of the International Union for Science and Technology Innovation, the Vice President of the China Semiconductor Industry Association IC Design Branch, the President of the China RISC-V Industry Consortium, the Vice President and the Expert Committee Member of the Automotive Electronics Industry Alliance, the President of the Shanghai Open Processor Innovation Center, the Vice President of Shanghai Integrated Circuit Industry Association, the Vice Chairman of the Expert Committee of the Shanghai IC Industry Cluster Development Promotion Institution, and the President of Berkeley Club of Shanghai.

Dr. Dai received his B.A. degree in Computer Science and his Ph.D. degree in Electrical Engineering from the University of California at Berkeley. He was a professor in the department of Computer Engineering at the University of California at Santa Cruz.

MEET THE SPEAKERS

MARC CANEL

Vice President, Business Development

Ventana Micro Systems

Marc Canel has extensive experience in the processor industry, driving ecosystems and business development for more than 30 years. He is Vice President of Business Development at Ventana Micro Systems, driving the integration of Ventana's world class RISC-V products across markets. Prior to Ventana, he was at Imagination Technologies where he was Vice President of Business Development promoting graphics and compute products. Prior to Imagination, he was at Arm where he was Vice President of Security Technologies, driving the rollout of security across the Arm ecosystem. Prior to Arm, he was a Vice President of Product Management at Qualcomm, driving the rollout of content protection and privacy management technologies. He also worked on the software ecosystem of Qualcomm, supporting the OEMs customers looking for complete solutions. Prior to Qualcomm, he was at IBM where he had various technical and product management roles in the development of data networking products.

MEET THE SPEAKERS

Minyu Xiao

Associate Partner

McKinsey & Company

- Minyu is Associate partner from McKinsey Shanghai office, and he leads McKinsey Industrial IOT hub Marketing & Sales serviceline
- In Minyu's past years at McKinsey, Minyu focused mainly helping semiconductor and tech players on future growth strategy, new business building and M&A, his selected experience includes:
  - — Helped global leading backend packing player with cross-boarder M&A
  - — Shortened time-to-market for a semiconductor design house in Greater China region
  - — Conducted commercial due diligence on a leading semiconductor equipment manufacturer
- Prior to McKinsey, Minyu obtained his Ph.D. in materials chemistry from University of Michigan, Ann Arbor

MEET THE SPEAKERS

HASSAN TRIQUI

Co-Founder, CEO & President

Secure-IC

Hassan Triqui is Co-Founder, CEO and President of Secure-IC, rising leader and the only global provider of end-to-end cybersecurity solutions for embedded systems and connected objects. Hassan has over 25 years of experience in the technology sector. Prior to spearheading Secure-IC's development into a major player in embedded cybersecurity solutions, he was a former senior executive at Thales and Technicolor Thomson.

Hassan holds a Master of Science in Electrical Engineering from the Institut National des Sciences Appliquées (INSA), as well as a Master of Business Administration from Rennes School of Business.

Hassan is a pioneer, a Brittany Tech patriot, and passionate about providing solutions that generate the real trust that clients deserve.

MEET THE SPEAKERS

HONGYU WANG

Bosch Sensortec GmbH Regional President APAC

Vice President of Bosch Semiconductors China

Mr. Hongyu Wang is the President of Bosch Sensortec Asia Pacific and, as of August 2024, the Vice President of Bosch Semiconductors China. With nearly 18 years of experience in the sensor and semiconductor industry, he joined Bosch in 2006 and has since held various roles across multiple divisions and regions.

Mr. Wang began his career at Bosch Corporate Research in Stuttgart, focusing on hardware and algorithm development for sensor-related digital signal processing. In 2009, he moved to Bosch Automotive Electronics (Suzhou) as the Manager of Electronic System Development, and in 2010, joined Bosch Sensortec (Shanghai) as an ASIC Project Manager and Department Head. He later transitioned to BSH Home Appliances (Nanjing) in 2018, overseeing electronic systems and software development, and was appointed Head of the Global Electronics and Motor Division (Greater China) in late 2019.

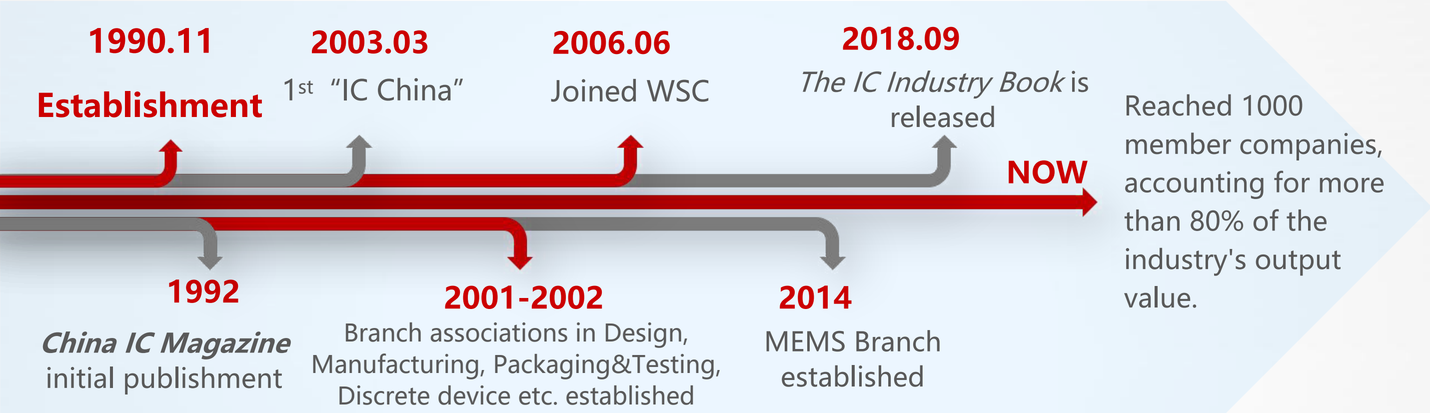
He holds a Bachelor's degree in Electrical Engineering from Zhejiang University and a Master's degree in Electrical Information Technology from the University of Stuttgart.

Serve
Connect
Communicate

About CSIA

CSIA is a national non-profit social organization voluntarily established by units, experts and other related supporting enterprises and institutions in the semiconductor field engaged in the manufacturing, design, scientific research, application, academia, semiconductor discrete devices, semiconductor materials and equipment etc..

CSIA is China's **sole national-level** non-governmental society organization for the semiconductor industry.



1990.11
Establishment

1992
China IC Magazine initial publishment

2001-2002
Branch associations in Design, Manufacturing, Packaging&Testing, Discrete device etc. established

2003.03
1st "IC China"

2006.06
Joined WSC

2014
MEMS Branch established

2018.09
The IC Industry Book is released

NOW
Reached 1000 member companies, accounting for more than 80% of the industry's output value.

International Cooperation & Some CSIA Members

Cooperation with international associations

CSIA joined the WSC in June 2006. CSIA actively promotes all-round and multi-level cooperation with foreign semiconductor industry, and promotes the development of mutually beneficial and win-win cooperation.

Including SIA in China
and
SIA in Chinese Taipei

CSIA has more than 1,000 members covering the entire semiconductor industry chain, with nearly 150 foreign member companies.

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Under the its unique "Silicon Platform as a Service" (SiPaaS) business model, VeriSilicon is committed to providing customers with platform-based, all-around, one-stop custom silicon services and semiconductor IP licensing services leveraging its in-house semiconductor IP. For more information, please visit: www.verisilicon.com.

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The China Semiconductor Industry Association (CSIA) is a national non-profit social organization voluntarily formed by entities, experts, and other supporting enterprises and institutions within the semiconductor sector, encompassing manufacturing, design, scientific research, application, academia, semiconductor discrete devices, materials, and equipment. Established in November 1990, CSIA stands as China's sole national-level non-governmental society organization dedicated to the semiconductor industry. With over 1000 member companies, which collectively contribute to more than 80% of the industry's output value, CSIA boasts a robust membership base.

CSIA has branch associations including Design, Manufacturing, Packaging & Testing, Discrete Devices, and MEMS, reflecting the diverse facets of the semiconductor industry. CSIA's mission is to foster an open platform for industrial collaboration, aiming to become the most influential non-governmental industrial organization in the field.

CSIA’s core services encompass Industry statistics & analysis, Consulting Services, International Cooperation, and training programs etc., tailored to meet the evolving needs of members. CSIA organizes several high-profile events, including IC China, which is the sole international large-scale industry exhibition sponsored by CSIA. IC China has successfully been held for 20 consecutive years, attracting global participation and showcasing the latest innovations.

CSIA emphasizes regional and international cooperation, with business penetration in various local provinces and cities. CSIA’ international outreach extends through cooperation with global associations; notably, CSIA joined the World Semiconductor Council (WSC) in June 2006, actively promoting comprehensive and multilevel collaboration with foreign semiconductor industries to foster mutually beneficial and win-win partnerships.

CSIA maintains excellent communication channels with relevant Chinese Ministries and Commissions, striving to serve as a pivotal bridge between enterprises and the government, facilitating seamless information flow and policy advocacy for the advancement of the semiconductor industry in China.

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gsaglobal.org

Global Semiconductor Alliance

@globalsemi

Global Semiconductor Alliance

GSA全球半导体联盟

AWARDS CELEBRATION

GSA 2024

DECEMBER 5 | SANTA CLARA, CA

GLOBAL SEMICONDUCTOR ALLIANCE 30 YEARS 1994-2024